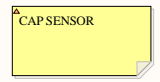
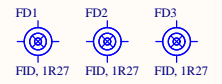


PMOD Interface Type 6A (expanded I2C)

Pin #	Signal	Direction (relative to host)	Alternate Signal	Direction (relative to host)
1	NC	In	INT	In
2	NC	Out	RESET	Out
3	SCL	In/Out	-	-
4	SDA	In/Out	-	-
5	GND	-	-	-
6	VCC	-	-	-
7	GPIO	In/Out	-	-
8	GPIO	In/Out	-	-
9	GPIO	In/Out	-	-
10	GPIO	In/Out	-	-
11	GND	-	-	-
12	VCC	-	-	-



Rubber Foot, Black, 6.4mm dia, 2.1mm high
FOOT-000003-01

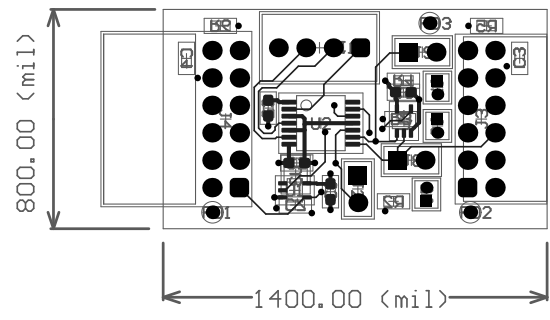


RENESAS

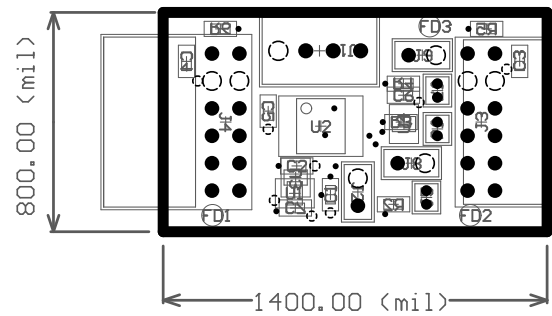
710 Slater Rd Morrisville
Suite 200 NC 27560

Title
US082-ZSSC3123EVZ Rev A.SchDoc

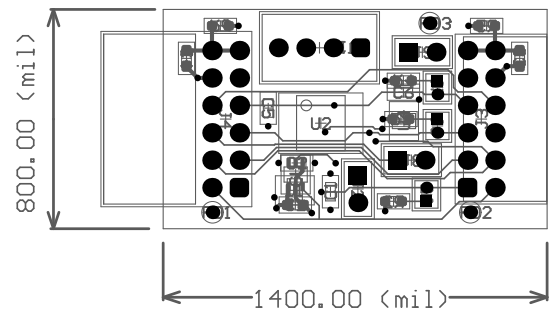
Size: B | Number: | Revision: A
Date: 11/6/2024 | Sheet 1 of 1
File: US082-ZSSC3123EVZ Rev A.SchDoc



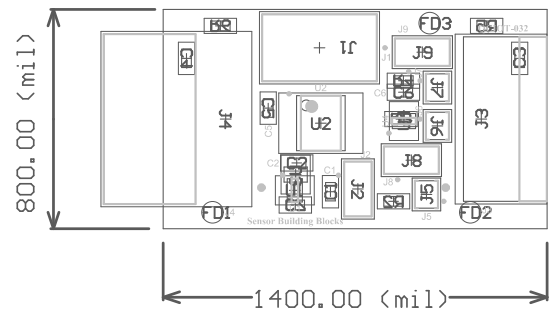
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Date: 11/6/2024
Layer Name: Top Layer
Company: RENESAS



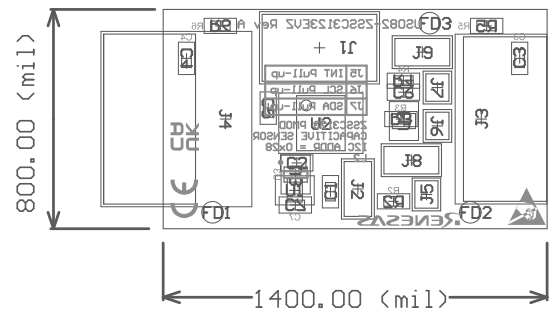
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Date: 11/6/2024
Layer Name: Int1 (GND) (GND)
Company: RENESAS



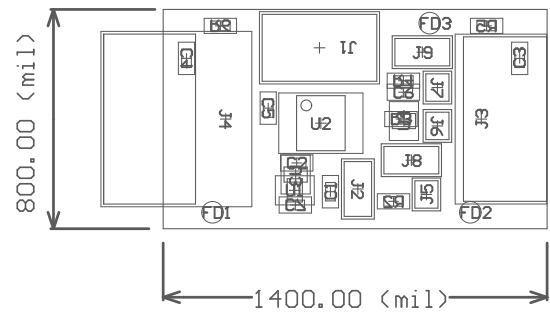
Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Bottom Layer
Company: RENESAS



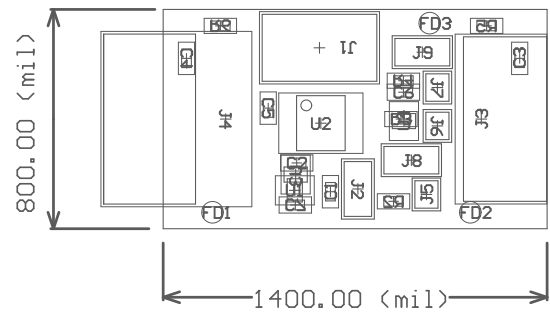
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Date: 11/6/2024
Layer Name: Top Silkscreen Overlay
Company: RENESAS



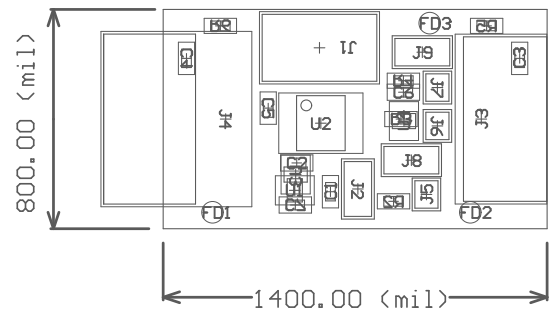
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 Date: 11/6/2024
 Layer Name: Bottom Silkscreen Overlay
 Company: RENESAS



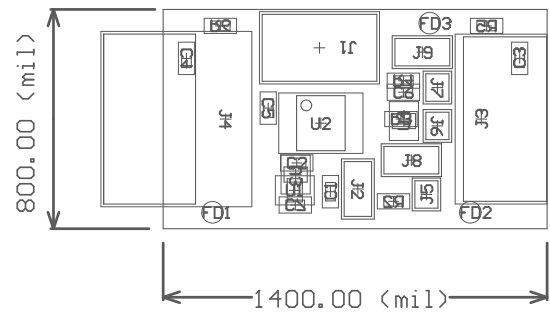
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Date: 11/6/2024
Layer Name: Mechanical 1
Company: RENESAS



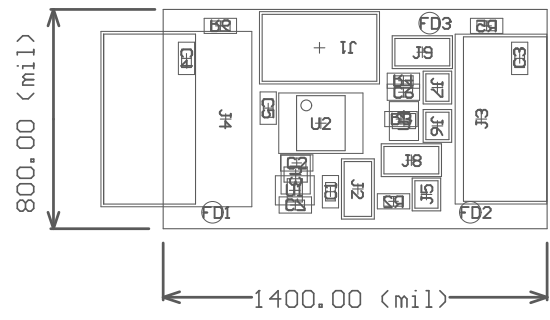
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Date: 11/6/2024
Layer Name: Top Designator
Company: RENESAS



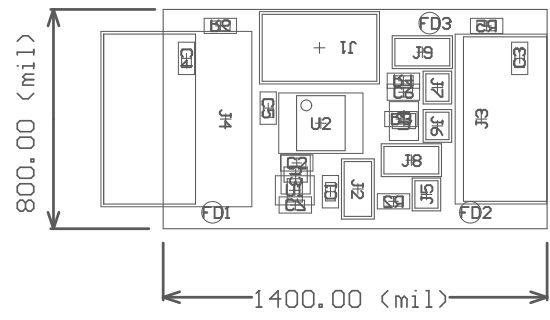
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 Date: 11/6/2024
 Layer Name: Bottom Designator
 Company: RENESAS



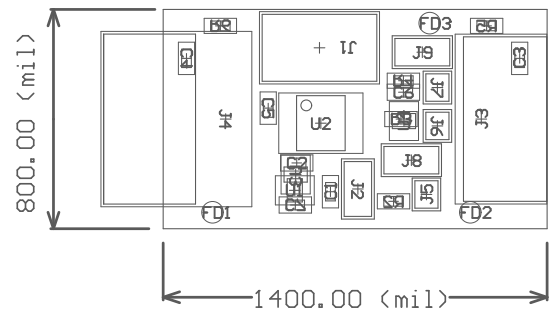
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Date: 11/6/2024
Layer Name: Top 3D Body
Company: RENESAS



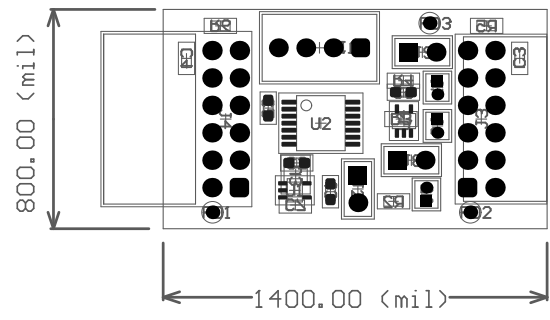
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Date: 11/6/2024
Layer Name: Bottom 3D Body
Company: RENESAS



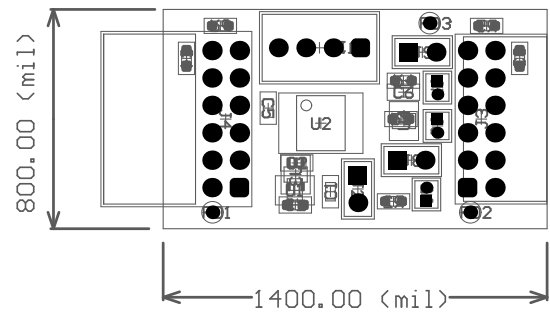
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Date: 11/6/2024
Layer Name: Top Courtyard
Company: RENESAS



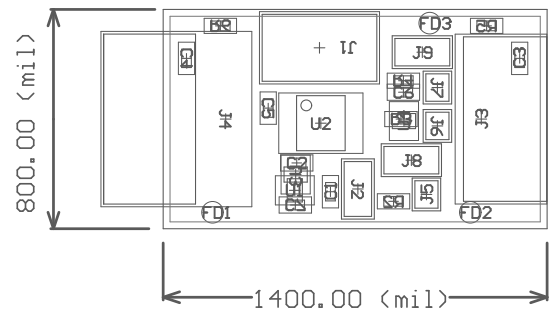
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Date: 11/6/2024
Layer Name: Bottom Courtyard
Company: RENESAS



Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Top Pad Master
Company: RENESAS

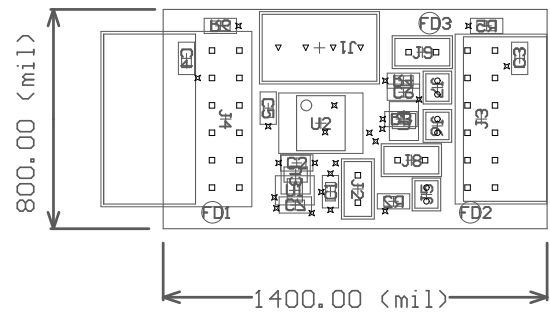


Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Bottom Pad Master
Company: RENESAS



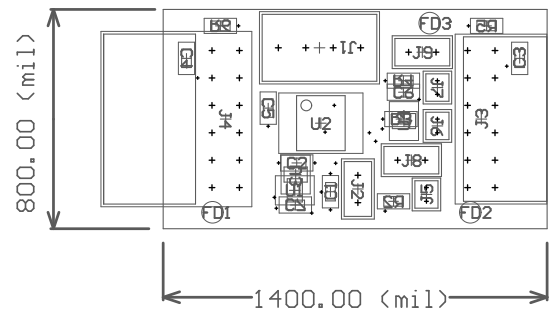
Filename: US082-ZSSC3123EUV Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Keep Out Layer
Company: RENESAS

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
▽	4	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	Pad	<Mixed>	<Mixed>
○	6	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	Pad	<Mixed>	<Mixed>
✕	23	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v61h25m0mx0
□	30	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	Pad	<Mixed>	<Mixed>
	63 Total							



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-003	1.00mil	4	
	Top Surface Finish	Nickel, Gold	0.16mil		
1	Top Layer	CF-004	1.38mil		
	Dielectric 1	PP-008	3.10mil	4.1	
	Dielectric 2	PP-013	3.80mil	4.3	
2	Int1 (GND)	CF-004	1.38mil		
	Dielectric 3	Core-042	39.00mil	4.6	
3	Int2 (PWR)	CF-004	1.38mil		
	Dielectric 4	PP-013	3.80mil	4.3	
	Dielectric 5	PP-008	3.10mil	4.1	
4	Bottom Layer	CF-004	1.38mil		
	Bottom Surface Finish	Nickel, Gold	0.16mil		
	Bottom Solder	SM-003	1.00mil	4	
	Bottom Overlay				

Filename: US082-ZSSC3123EUV Rev A.PcbDoc
 Date: 11/6/2024
 Layer Name: Drill Drawing For (Top Layer - Bottom Layer)
 Company: RENESAS



Filename: US082-ZSSC3123EUV Rev A.PcbDoc
 Date: 11/6/2024
 Layer Name: Drill Guide For <Top Layer - Bottom Layer>
 Company: RENESAS